

What is claimed is:

- 1 1. A system for decapsulating an integrated
2 circuit package that is mounted to a printed circuit
3 board, comprising:
4 a source of a decapsulation fluid;
5 a tray that supports the printed circuit board;
6 an injection head that is located adjacent to the
7 integrated circuit package, said injection head has a
8 nozzle and a return port that are coupled to said
9 source of decapsulation fluid to introduce the
10 decapsulation fluid to the integrated circuit package;
11 and,
12 a gasket that seals said injection head to the
13 integrated circuit package.
- 1 2. The system as recited in claim 1, further
2 comprising a clamp that clamps said injection head onto
3 the integrated circuit package.
- 1 3. The system as recited in claim 1, wherein said
2 source of decapsulation fluid includes an extender that
3 is coupled to a nozzle that provides the decapsulation
4 fluid.

1 4. The system as recited in claim 3, further
2 comprising a pair of tubes that couple said extender to
3 said injection head.

1 5. The system as recited in claim 4, further
2 comprising a pair of valves that control a flow of the
3 decapsulation fluid through said tubes.

1 6. The system as recited in claim 1, wherein said
2 tray includes a stub that supports the printed circuit
3 board and which is plugged into a substrate of said
4 tray.

1 7. A system for decapsulating an integrated
2 circuit package that is mounted to a printed circuit
3 board, comprising:

4 a substrate;

5 a clamp that is mounted to said substrate, said
6 clamp having a leg portion that supports the printed
7 circuit board;

8 a stub that is plugged into said substrate and
9 which supports the printed circuit board;

10 a decapsulation fluid unit which has a nozzle that
11 provides a decapsulation fluid, and a return port that
12 receives the decapsulation fluid;

13 an extender that has an intake port that is in
14 fluid communication with an outlet port of said
15 extender and said nozzle of said decapsulation fluid
16 unit, and an exhaust port that is in fluid
17 communication with an inlet port of said extender and
18 said return port of said decapsulation fluid unit;

19 an injection head that is clamped to the
20 integrated circuit package by said clamp, said
21 injection head has a nozzle that is in fluid
22 communication with an inlet port of said injection
23 head, and a return port that is in fluid communication
24 with an outlet port of said injection head;

25 a first tube that couples said outlet port of said
26 extender with said inlet port of said injection head;

27 a second tube that couples said inlet port of said
28 extender with said outlet port of said injection head;

29 and,

30 a gasket that seals said injection head to the
31 integrated circuit package.

1 8. The system as recited in claim 4, further
2 comprising a pair of valves that control a flow of the
3 decapsulation fluid through said tubes.

1 9. A method for decapsulating an integrated
2 circuit package that is mounted to a printed circuit
3 board, comprising the steps of:

- 4 a) providing an injection head that sprays a
5 decapsulation fluid;
6 b) placing the printed circuit board onto a tray;
7 c) clamping said injection head onto the
8 integrated circuit package; and,
9 d) spraying the decapsulation fluid onto the
10 integrated circuit package.

1 10. The method as recited in claim 9, further
2 comprising the step of moving a stub that is plugged
3 into said tray and which supports the printed circuit
4 board before the printed circuit board is placed onto
5 said tray.